

ABSTRACT

A polishing apparatus has a turntable with a polishing cloth attached thereto and a top
5 ring for holding and pressing a workpiece to be polished against the polishing cloth under
a certain pressure. The polishing apparatus also has a first dressing unit having a contact-
type dresser for dressing the polishing cloth by bringing the contact-type dresser in contact
with the polishing cloth, and a second dressing unit having a noncontact-type dresser for
dressing the polishing cloth with a fluid jet applied therefrom to the polishing cloth. The
10 contact-type dresser comprises a diamond dresser or an SiC dresser.